

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image























High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 12, 90°, Solder pin length (I): 1.5 mm, tinned, black, Tape
Order No.	<u>1374890000</u>
Туре	SL-SMT 5.08HC/12/90LF 1.5SN BK RL
GTIN (EAN)	4050118175974
Qty.	300 pc(s).
Product data	IEC: 400 V / 27.5 A
	UL: 300 V / 18.5 A
Packaging	Tape

Creation date May 11, 2025 5:55:00 PM CEST



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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	10 mm	Height (inches)	0.394 inch
Height of lowest version	8.5 mm	Width	70.76 mm
Width (inches)	2.786 inch	Net weight	5.25 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connec-	Pitch in mm (P)	
	tion		5.08 mm
Pitch in inches (P)	0.2 "	Outgoing elbow	90°
Number of poles	12	Number of solder pins per pole	1
Solder pin length (I)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	L1 in mm	55.88 mm
L1 in inches	2.2 "	Number of rows	1
Pin series quantity	2	Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged
Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 un- plugged	Protection degree	IP20
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	9 N	Pulling force/pole, max.	7 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface		Layer structure of solder connection	13 μm Ni / 24 μm Sn
	tinned		matt
Layer structure of plug contact	13 μm Ni / 24 μm Sn	Storage temperature, min.	
	matt		-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A



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Technical data

Rated data acc. to UL 1059

Institute (UR)	<i>71</i> 2	Certificate No. (UR)	
			E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

ESD Level packaging	static dissipative	Packaging	Tape
VPE length	351 mm	VPE width	344 mm
VPE height	90 mm	Tape depth (T2)	13 mm
Tape width (W)	88 mm	Tape pocket depth (K0)	12.5 mm
Tape pocket height (A0)	12.3 mm	Tape pocket width (B0)	71.4 mm
Tape pocket separation (P1)	16 mm	Tape hole separation (E)	1.75 mm
Tape pocket separation (F)	42.2 mm	Tape reel diameter Ø (A)	330 mm
Surface resistance	Rs = $10^9 - 10^{12} \Omega$		

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01
ECLASS 15.0	27-46-02-01		

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%



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Imp	orta	nt r	note
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IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized stan- dards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	Gold-plated contact surfaces on request
	Rated current related to rated cross-section & min. No. of poles.
	• Diameter of solder eyelet D = 1.4+0.1mm
	• Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles
	• P on drawing = pitch
	 Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
	 In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load
	 Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36

Approvals

Approvals	,
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months

Approvals MAMID	https://mdcop.weidmueller.com/mediadelivery/rendition/900_319262/-T1z1mm-S800/
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

Downloads

Engineering Data	CAD data – STEP
Product Change Notification	PCN 2015 208 PL30X SC-SMT SL SMT 3.xx 5.xx neue Tapeverpackung Step 4 DE PCN 2015 208 PL30X SC-SMT SL SMT 3.xx 5.xx new Tape Packaging Step 4 EN Changeover to ESD bags for "Tape on Reel" products Umstellung auf ESD-Beutel bei "Tape on Reel" Produkten
Catalogues	<u>Catalogues in PDF-format</u>
Brochures	FL DRIVES EN FL DRIVES DE
White paper surface mount technology	Download Whitepaper



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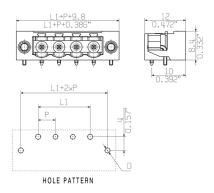
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Drawings

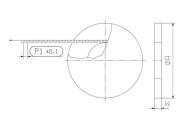
Product image



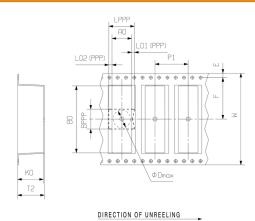
Dimensional drawing



Dimensional drawing



Dimensional drawing



Example of use



Product benefits



Safe power transmission Proven properties



Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

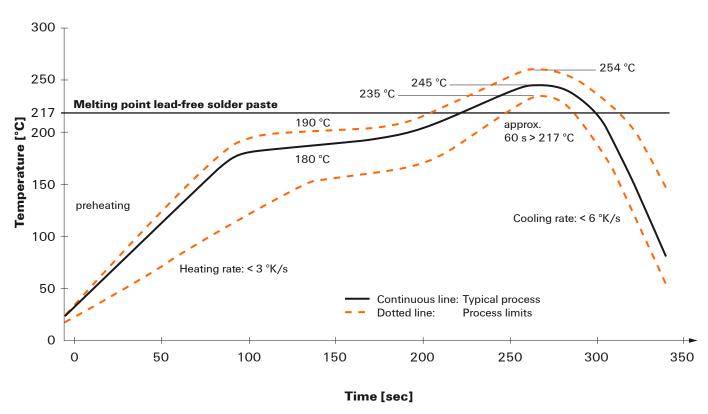


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.